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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/676,645	10/01/2003	Gyung-Su Cho	DPP-GZ-2007-0009-US-00	7874
36872 7590 04/01/2008 THE LAW OFFICES OF ANDREW D. FORTNEY, PH.D., P.C.			EXAMINER	
401 W FALLBI	ROOK AVE STE 204		NADAV, ORI	
FRESNO, CA 93711-5835			ART UNIT	PAPER NUMBER
			2811	
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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

	Application No.	Applicant(s)
	10/676,645	CHO, GYUNG-SU
Office Action Summary	Examiner	Art Unit
	Ori Nadav	2811
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the c	correspondence address
A SHORTENED STATUTORY PERIOD FOR REPL WHICHEVER IS LONGER, FROM THE MAILING D - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailin earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tin will apply and will expire SIX (6) MONTHS from e, cause the application to become ABANDONE	N. nely filed the mailing date of this communication. D (35 U.S.C. § 133).
Status		
Responsive to communication(s) filed on <u>14 F</u> This action is FINAL . 2b) ☐ This action is FINAL . Since this application is in condition for alloware closed in accordance with the practice under B	s action is non-final. nce except for formal matters, pro	
Disposition of Claims		
4)	wn from consideration.	
Application Papers		
9) The specification is objected to by the Examine 10) The drawing(s) filed on is/are: a) accomposed and applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Example 11.	cepted or b) objected to by the liderawing(s) be held in abeyance. See tion is required if the drawing(s) is objected.	e 37 CFR 1.85(a). jected to. See 37 CFR 1.121(d).
Priority under 35 U.S.C. § 119		
12) ☐ Acknowledgment is made of a claim for foreign a) ☐ All b) ☐ Some * c) ☐ None of: 1. ☐ Certified copies of the priority document 2. ☐ Certified copies of the priority document 3. ☐ Copies of the certified copies of the priority application from the International Burea * See the attached detailed Office action for a list	ts have been received. ts have been received in Applicati rity documents have been receive u (PCT Rule 17.2(a)).	on No ed in this National Stage
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal F 6) Other:	ate

DETAILED ACTION

Claim Rejections - 35 USC § 112

The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

Claims 1, 4-5, 8, 22-24, 27-32 and 34-37 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

The claimed limitation of a "the alloy", as recited in claim 1, is unclear as to whether "the alloy" is "the alloy layer" or a different element.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1, 4-5, 23-24, 27-32 and 34-37, as best understood, are rejected under 35 U.S.C. 102(e) as being anticipated by Matsubara (6,890,852).

Matsubara teaches in figure 1 and related text a semiconductor device comprising:

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a via within an insulation layer 16 over a metal line (located within semiconductor substrate 1);

a barrier metal layer 6 on a surface of the via;

a copper layer 9 on the barrier metal layer within the via, the copper layer having vertical side surfaces that contact the barrier metal layer; and

an alloy layer 10 (column 10, lines 20-22) on an upper surface of the copper layer within the via, the alloy having a top surface that is coplanar with or lower than a top surface of the insulation layer, wherein vertical side surfaces of the alloy layer contact (make electrical contact) the barrier metal layer, and the alloy layer consists essentially of copper and a low melting point metal selected from the group consisting of aluminum, lead, and silver, wherein

the thickness of the alloy layer is less than a thickness of the copper layer, wherein

a protection layer 26 (see figure 12) comprising silicon nitride or silicon oxynitride over the cooper layer except for the portion of the copper layer within the via, wherein the barrier metal comprises a metal selected from the group consisting of Ti, Ta, TiN, and TaN, and having a thickness between 200 and 800A

an insulation layer 101 comprises oxide over the semiconductor device, wherein the via is within the insulation layer, wherein

the barrier metal layer prevents the diffusion of copper from the copper layer into the insulating layer, wherein

the alloy layer is completely within the via and exposed through an opening in the protection layer, wherein

the barrier metal layer covers all surfaces of the via and contacts the insulating layer, and

wherein a thickness of the alloy layer being less than a thickness of the metal line.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 8 and 22, as best understood, are rejected under 35 U.S.C. 103(a) as being unpatentable over Matsubara in view of Liu et al. (6,638,867).

Regarding claims 5 and 22, Matsubara teaches in figure 1 and related text substantially the entire claimed structure, as applied to claim 1 above, except a width of the boding pad is less than a width of via.

Liu et al. teach in figure 2 and related text a width of the bonding pad 24 is less than a width of via.

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It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use a width of the bonding pad being less than a width of via in Matsubara's device in order to reduce the size of the device.

Response to Arguments

Applicant argues that Matsubara does not teach thick copper layer 10 and thin copper layer 9 formed of different materials.

Claim 1 recites a bonding pad comprising a copper layer and a copper alloy layer. The broad recitation of the claim does not require that the copper layer and the alloy layer comprise different materials, since the copper layer can include additional materials therein.

Although the claims are interpreted in light of the specification, limitations from the specification are not read into the claims. See *In re Van Geuns*, 988 F.2d 1181, 26 USPQ2d 1057 (Fed. Cir. 1993).

Applicant argues that Matsubara does not teach a metal line consisting essentially of copper in the via over the barrier metal layer having vertical side surfaces that contact the barrier metal layer.

Matsubara teaches a metal line 9 consisting essentially of copper in the via over the barrier metal layer having vertical side surfaces that making electrical contact with the barrier metal layer 6.

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Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ori Nadav whose telephone number is 571-272-1660.

The examiner can normally be reached between the hours of 7 AM to 4 PM (Eastern

Standard Time) Monday through Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Lynne Gurley can be reached on 571-272-4670. The fax phone number for

the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent

Application Information Retrieval (PAIR) system. Status information for published

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O.N. 3/31/2008 /ORI NADAV/ PRIMARY EXAMINER TECHNOLOGY CENTER 2800